



PRODUCT BULLETIN
Generic Copy

23 Oct 2007

SUBJECT: ON Semiconductor Product Bulletin #16059

TITLE: Package Pin Removal – NCP1396

PROPOSED FIRST SHIP DATE: 23 Oct 2007

AFFECTED PRODUCT DIVISION: Analog IC

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or Scott.Brow@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact your local ON Semiconductor sales office.

DESCRIPTION AND PURPOSE:

ON Semiconductor wishes to notify all customers who have purchased the following parts of a future improvement.

In order to improve the creepage distance on the current NCP1396 device family, ON Semiconductor is removing Pin 13 from the package. Pin 13 is currently a "No Connect" pin and removing the pin will have no affect on the performance of the device. The pin is physically removed from the lead frame design and there are no changes to any other package dimensions or layout.

For assistance, please contact;

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AFFECTED DEVICE LIST

NCP1396ADR2G
NCP1396BDR2G